CLAIMS

[Claim 1] A resin sheet, comprising

a base sheet containing a polystyrene-based resin,

wherein a maximum puncture elastic modulus calculated by a procedure described below is 2.4 to 6.4 MPa,

[Calculation Procedure of Maximum Puncture Elastic Modulus]

a measurement sample is fixed to a flat plate-shaped jig having a hole with a diameter of 1.0 mm provided in a center portion, a load L (N) and a strain amount ε in a puncture direction when perpendicularly puncturing a surface of the measurement sample with a needle having a tip in the shape of a circular flat surface (a diameter of 0.8 mm) at a rate of 0.5 mm/minute are measured under an environment of 23°C, and a value when a ratio of a stress difference to a strain amount difference calculated by Expression: $(\Delta L/S)/\Delta\varepsilon$ (in the expression, S indicates an area (mm^2) of a tip surface of the needle) is maximized at $0.1 \leq \varepsilon \leq 5.0$ is set as the maximum puncture elastic modulus.

[Claim 2] The resin sheet according to claim 1,

wherein when performing dynamic viscoelasticity measurement, a storage modulus E'1 at 25°C is 1.0×10^8 Pa or more and 1.0×10^{10} Pa or less, and a storage modulus E'2 at Loss Tangent Peak Temperature + 20°C is 1.0×10^6 Pa or less.

[Claim 3] The resin sheet according to claim 1 or 2,

wherein the base sheet contains one or more types of resins of a general-purpose polystyrene resin and an impact-resistant polystyrene resin in a total of 50% by mass or more, on the basis of a total amount of a styrene-based resin.

[Claim 4] A resin sheet, comprising

a base sheet containing a thermoplastic resin,

wherein when performing dynamic viscoelasticity measurement, a storage modulus E'1 at 25°C is 1.0×10^8 Pa or more and 1.0×10^{10} Pa or less, and a storage modulus E'2 at Loss Tangent Peak Temperature + 20°C is 1.0×10^6 Pa or less.

[Claim 5] A container that is a compact of the resin sheet according to any one of claims 1 to 4.

[Claim 6] A carrier tape that is a compact of the resin sheet according to any one of claims 1 to 4 and is provided with an accommodation portion capable of accommodating a commodity.

[Claim 7] An electronic component packaging, comprising:

the carrier tape according to claim 6;

an electronic component accommodated in the accommodation portion of the carrier tape; and

a cover film adhering to the carrier tape as a lid material.